

TIMOTHY E. MURPHY

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ACADEMIC POSITIONS

University of Idaho College of Law, Boise/Moscow, Idaho

Assistant Professor of Law; 2021-Present

Courses taught: Contracts, Introduction to Intellectual Property, Jurisprudence,
Internet Law, Patent Law and Practice, Patent Drafting, Lawyering Process:
Transactions, Entrepreneurship Law Clinic

University of Michigan Law School, Ann Arbor, Michigan

Clinical Assistant Professor of Law; 2020-2021

University of Idaho College of Law, Boise/Moscow, Idaho

*Visiting Associate Professor of Law; Director, Entrepreneurship Law Clinic; Director, Idaho
Patent Pro Bono Program; 2018-2020*

Concordia University School of Law, Boise, Idaho

Adjunct Professor, 2015-2018

Boise State University, Boise, Idaho

Adjunct Professor, 2010

EDUCATION

University of Michigan Law School, Ann Arbor, Michigan

Juris Doctor, May 2008

University of Michigan, Ann Arbor, Michigan

Master of Science in Electrical Engineering, May 2004

Specialized in Solid State Electronics and Advanced Materials

Boise State University, Boise, Idaho

Bachelor of Science in Electrical Engineering, May 2002

Magna Cum Laude

LAW-RELATED PUBLICATIONS & WORKS IN PROGRESS

- Work-in-Progress: *Separating the Creator from the Owner in U.S. Intellectual Property Regimes*, early stage, abstract submitted for ISHTIP 2024.
- Submitted: *Can Trade Secrets Protection of Routine Business Information Be Justified?*, submitted for publication in Spring 2024.
- Forthcoming: *Do Androids Dream of Economic Incentives*, forthcoming in Akron Law Review in Spring 2024.

- Timothy Murphy, *Can't Get It out of My Head: Trade Secrets Liability for Remembered Information*, 2023 WIS. L. REV. 1929 (2023).
- Timothy Murphy, *Memorizing Trade Secrets*, 57 Rich. L. Rev. 533 (2023).
- Timothy Murphy, *How Can a Departing Employee Misappropriate Their Own Creative Outputs?*, 66 Vill. L. Rev. 529 (2021).
- Timothy Murphy, *An Instance of Open Hardware: A Different Approach to Free and Open Source Hardware Licensing*, 30 Fordham Intell. Prop. Media & Ent. L. J. 1045 (2020).
- Timothy E. Murphy, *University of Idaho's Entrepreneurship Law Clinic: Providing Free Legal Services for Idaho Ventures*, The Advocate, Vol. 62, No. 3/4, at p. 34.

LAW-RELATED ACADEMIC PRESENTATIONS

- Trade Secret Protection for Routine Business Information, WIPIP 2022, Feb. 2-3, 2024.
- Trade Secrets Issues for AI-generated Information, University of Akron School of Law IP Scholar's Forum, December 8, 2023.
- Trade Secret Protection for Routine Business Information, Intellectual Property Scholars Conference, August 3-4, 2023.
- Trade Secret Protection for Routine Business Information, 2023 Junior IP Scholars Association Workshop, August 1-2, 2023
- *Taxonomy of Remembered Trade Secret Information*, 2023 Trade Secret Workshop, January 13, 2023
- *Employee Trade Secret Issues*, 2022 Trade Secret Workshop, June 10-11, 2022
- *Memorizing Trade Secrets*, WIPIP 2022, Feb. 18-19, 2022
- *Trade Secrets Liability for Remembered Information*, Junior IP Scholars Association Workshop, July 22-23, 2021
- *Remote Teaching Approaches for Inclusivity in Transactional Clinic Seminars*, Northwest Clinical Law Conference, Nov. 5-7, 2020.

SELECTED PROFESSIONAL EXPERIENCE

Micron Technology, Inc., Boise, Idaho (2010-2018)

Sr. Patent and Trademark Counsel; Technology Licensing Counsel

Primary Practice Areas: patent and trademark portfolio management; patent litigation; intellectual property licensing; M&A contract drafting and diligence; commercial contracts; trade secret program management

Zarian, Midgley, & Johnson, PLLC, Boise, Idaho (2010)

Associate Attorney

Primary Practice Areas: patent prosecution; commercial and IP litigation

Marger Johnson & McCollom, P.C., Portland, Oregon (2006-2009)

Associate Attorney; Patent Agent

Primary Practice Areas: Patent and trademark prosecution; commercial and IP litigation

Micron Technology, Inc., Boise, Idaho (1995-2002)
DRAM R&D Engineer; Manufacturing Engineer; Manufacturing Technician

U.S. Navy, Norfolk, Virginia (1988-1994)
Machinist's Mate (Nuclear)

Received honorable discharge and several commendations including the Southwest Asia Service Medal for participation in Operation Desert Storm

PRO BONO EXPERIENCE

- Guardian *ad litem* representations in child protection cases (2014-2019)
- Hague Convention child abduction case (2016-2017)
- Divorce/custody cases (2009-2016)
- Small business dispute for refugee family (2014)
- § 1983 prisoner civil rights claim (2009-2010)

BAR ADMISSIONS

- Idaho (inactive)
- U.S. Patent and Trademark Office (Reg. No. 59,092)

UNIVERSITY SERVICE

- U of I Faculty Senate, Senator for SW Idaho Region, AY2022 to present
- University Assessment and Accreditation Committee, Member, AY2021 to present
- University Safety and Loss-Control Committee, Member, AY2022 to present
- College of Law Curriculum Committee, Chair, AY2023-24
- College of Law DEI Committee, Member, AY2023-24
- College of Law Dean's Advisory Committee, Member, AY2023-24
- College of Law Dean Search Advisory Committee, Member, AY2023-24
- College of Law Academic Hearing Board, Chair, AY2022-23
- College of Law Curriculum Committee, Member, AY2022-23
- College of Law Technology Committee, Member, AY2021-22

LOCAL COMMUNITY ENGAGEMENT

- Coach - 2021 and 2024 USPTO National Patent Application Drafting Competitions
- Intellectual Property Section of the Idaho State Bar, Treasurer (2021-present), past Vice-Chair, Secretary, and member (2010-2020)
- Idaho Military Legal Alliance, Steering Committee member and Treasurer (2023-present)
- Coach – 2021-22 ABA Negotiation Competition
- Michigan Patent Pro Bono Program Review Committee (2020-2021)
- Panel Moderator, University of Idaho Critical Legal Studies Journal Symposium: *Technology in the Law: is it leveling the playing field?*, March 29, 2019

- Idaho Volunteer Lawyers Program, Policy Council member (2010-2020)
- Idaho Technology Council Tech2Market Committee, member (2018-2020)
- Idaho Military Legal Alliance, member (2018-2020)
- Kuna Entrepreneur's Bootcamp, (February 2019)
- Business and Corporate Law Section of the Idaho State Bar, member (2018-2019)
- Child Protection Section of the Idaho State Bar, member (2018-2019)
- Micron Legal Department Community Service Committee, Chairperson (2014-2018)

NATIONAL AND REGIONAL ENGAGEMENT

- AALS Clinical Section, Membership, Outreach, and Training Committee, member (2019-2020)
- AALS Conference on Clinical Legal Education, working group facilitator (May 2019)
- Northwest Clinical Law Conference, Planning Committee member (May-Nov. 2019)

AWARDS

- Alumni Award for Excellence Inspirational Mentor (2023)
- Denise O-Donnell-Day Pro Bono Award (2011)

PEER-REVIEWED TECHNICAL JOURNAL PUBLICATIONS

- T.E. Murphy, D.Y. Chen, E. Cagin, and J.D. Phillips, *Electronic Properties Of ZnO Epilayers Grown On C-Plane Sapphire By Plasma-Assisted Molecular Beam Epitaxy*, Proceedings from the 22nd North American Molecular Beam Epitaxy Conference, October 10-13, 2004, Banff, Canada, Journal of Vacuum Science and Technology B, Volume 23 (3), 1277-1280 (2005).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Growth And Electronic Properties Of ZnO Epilayers By Plasma-Assisted Molecular Beam Epitaxy*, Proceedings from the 2004 U.S. Workshop on the Physics and Chemistry of II-VI Materials, October 5-7, 2004, Chicago, Illinois, Journal of Electronic Materials, Volume 34 (6), 699-703 (2005).
- T. E. Murphy, J. O. Blaszczak, K. Moazzami, W. E. Bowen, And J. D. Phillips, *Properties Of Electrical Contacts On Bulk And Epitaxial n-Type ZnO*, Proceedings from the 46th TMS Electronic Materials Conference, June 23-25, 2004, Notre Dame, Indiana, Journal of Electronic Materials, Volume 34 (4), 389-394 (2005).
- T.E. Murphy, S. Walavalkar, and J.D. Phillips, *Epitaxial growth and surface modeling of ZnO on c-plane Al₂O₃*, Applied Physics Letters, Volume 85 (26), 6338-6340 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Electronic Properties Of Ferroelectric BaTiO₃/MgO Capacitors On GaAs*, Applied Physics Letters, Volume 85 (15), 3208-3210 (2004).
- D. Chen, T. E. Murphy, S. Chakrabarti, and J. D. Phillips, *Optical Waveguiding In BaTiO₃/MgO/Al_xO_y/GaAs Heterostructures*, Applied Physics Letters, Volume 85 (22), 5206-5208 (2004).

- D.Y. Chen, T.E. Murphy, and J.D. Phillips, *Deposition Of BaTiO₃ Thin Films And MgO Buffer Layers On Patterned GaAs Substrates for Integrated Optics Applications*, Materials Research Society 2003 Fall Meeting Proceedings, Volume 784, C11.23 (2004).
- T.E. Murphy, D.Y. Chen, and J.D. Phillips, *Integration of BaTiO₃ Ferroelectric Thin Films with GaAs for Functional Devices*, Proceedings of the 15th Biennial University/Government/Industry Microelectronics Symposium, June 30-July 2, 2003, Boise, Idaho (2003).

ISSUED PATENTS

- US Patent Number 7,732,882, *Method and system for electrically coupling a chip to chip package*, issued June 8, 2010.
- US Patent Number 7,489,875, *System and method for multiple bit optical data transmission in memory systems*, issued February 10, 2009.
- US Patent Number 7,355,273, *Semiconductor dice having back side redistribution layer accessed using through-silicon vias, methods*, issued April 8, 2008.
- US Patent Number 7,335,985, *Method and system for electrically coupling a chip to chip package*, issued February 26, 2008.
- US Patent Number 7,254,331, *System and method for multiple bit optical data transmission in memory systems*, issued August 7, 2007.
- US Patent Number 7,015,559, *Method and system for electrically coupling a chip to chip package*, issued March 21, 2006.
- US Patent Number 6,936,489, *Method and system for electrically coupling a chip to chip package*, issued August 30, 2005.
- US Patent Number 6,914,317, *Thin microelectronic substrates and methods of manufacture*, issued July 5, 2005.
- US Patent Number 6,831,301, *Method and system for electrically coupling a chip to chip package*, issued December 14, 2004.
- US Patent Number 6,800,930, *Semiconductor dice having back side redistribution layer accessed using through-silicon vias, and assemblies*, issued October 5, 2004.
- US Patent Number 6,693,342, *Thin microelectronic substrates and methods of manufacture*, divisional from 6,303,469, issued February 17, 2004.
- US Patent Number 6,303,469, *Thin microelectronic substrates and methods of manufacture*, issued October 16, 2001.

TECHNICAL CONFERENCE PRESENTATIONS

- 2005 American Society for Engineering Education Annual Conference and Exhibition, June 12-15, 2005, Portland, Oregon.
- 22nd North American Molecular Beam Epitaxy Conference, October 10-13, 2004, Banff, Alberta, Canada.
- The 2004 U.S. Workshop on the Physics and Chemistry of II-VI Materials, October 5-7, 2004, Chicago, Illinois.
- The 2004 TMS Electronic Materials Conference and Exhibition, June 23-25, 2004, South Bend, Indiana.

- 15th Biennial University/Government/Industry Microelectronics Symposium, June 30-July 2, 2003, Boise, Idaho. Oral Presentation.
- The 2003 TMS Electronic Materials Conference, June 25-27, 2003, Salt Lake City, Utah.